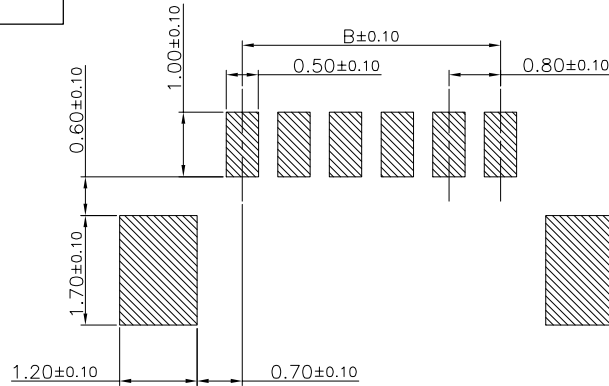


The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements

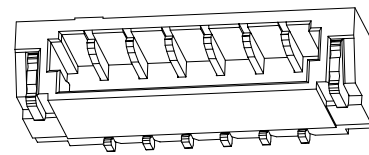
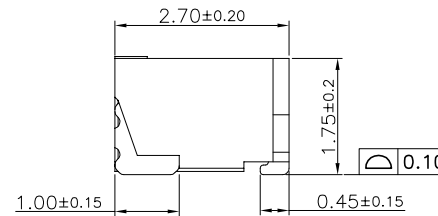
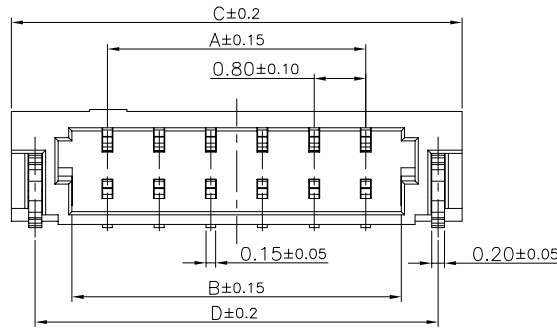
RoHS+HF



NO.1



RECOMMEND PCB LAYOUT



3D VIEW

NOTE:

1.MATERIAL SPECIFICATION:

1-1.HOUSING: LCP,UL94V-0

1-2.CONTACTS: PHOSPHOR BRONZE

1-3.SOLDER TABS: PHOSPHOR BRONZE

2.PLATING SPECIFICATION:

2-1.CONTACTS:

TIN/GOLD FLASH PLATED OVER ALL.

2-2.SOLDER TABS:

TIN/GOLD FLASH PLATED OVER ALL.

3.MECHANICAL PERFORMANCE:

3-1.RETENTIVITY FORCE: 0.2KGF/pin min

3-2.DURABILITY: 50 CYCLES.

4.ELECTRICAL PERFORMANCE:

4-1.CURRENT RATING: 0.5A AC/DC

RATED VOLTAGE : 30V AC/DC

4-2.CONTACT RESISTANCE: 30 mΩ MAX

4-3.INSULATION RESISTANCE: 100MΩ Min

4-4.DIELECTRIC WITHSTANDING : 200V

5.ENVIRONMENTAL PERFORMANCE:

5-1.OPERATING TEMPERATURE: -25°C~+85°C.

6.PACKAGE SPEC: REEL

7.P/N: D0801 W 9 1-1 XX 2 X X 0 A1

SERIES NO:

CONNECTOR:

W-WAFER

ANGLE:

9-90°

TYPE:

1-TYPE 1

ROW NO:

1-SINGLE ROW



COLOR:
A-BLACK
S-NATURE

PLATING:
A-ALL AU G/F
C-BRIGHE TIN
D-MATTE Tin

TERMIPOINT:
2-SMT

PIN Q' PY:
02~20

Circuit	Dimensions(mm)				Circuit	Dimensions(mm)			
	A	B	C	D		A	B	C	D
02	0.80	1.90	3.78	3.04	12	8.80	9.90	11.78	11.04
03	1.60	2.70	4.58	3.84	13	9.60	10.70	12.58	11.84
04	2.40	3.50	5.38	4.64	14	10.40	11.50	13.38	12.64
05	3.20	4.30	6.18	5.44	15	11.20	12.30	14.18	13.44
06	4.00	5.10	6.98	6.24	16	12.00	13.10	14.98	14.24
07	4.80	5.90	7.78	7.04	17	12.80	13.90	15.78	15.04
08	5.60	6.70	8.58	7.84	18	13.60	14.70	16.58	15.84
09	6.40	7.50	9.38	8.64	19	14.40	15.50	17.38	16.64
10	7.20	8.30	10.18	9.44	20	15.20	16.30	18.18	17.44
11	8.00	9.10	10.98	10.24					

REV.	REVISION RECORD	DATE
A0	NEW RELEASE	22.05.09
A1	PART NUMBER RENEWAL	23.09.12

GENERAL TOLERANCES	
LINEAR	ANGLES
0.0±0.35	X'REF±6°
0.00±0.25	X'±3°
0.000±0.10	X'X' ±2°

SCALE:	NAME	DATE
1:1	Wang_jr	23.09.12
APPROVED	Han_Gao	23.09.12
DESIGNER	LanXuan_Hou	23.09.12

PART.NO:	TITLE:
D0801W91-1XX2XX0	Pitch 0.80mm SUR单排90°卧贴 Wafer

DWG.NO:
ENDE05

REV: A1 SHEET: 1/2

